

# FRED KD0860UF.



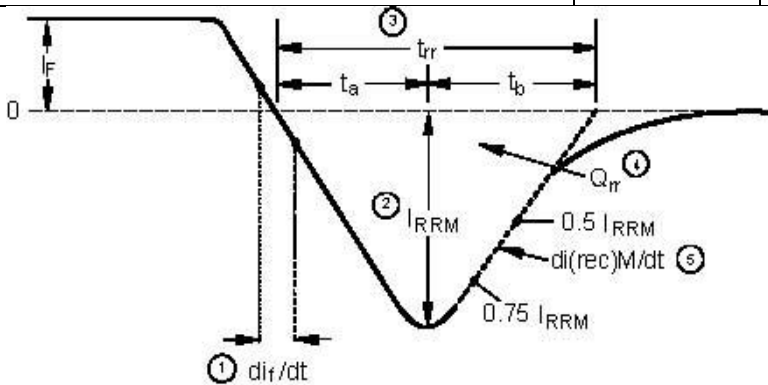
Rev.3. May . 2013



**VSP-MIKRON**

**8A/600V. Die Size-81\*81mil.**

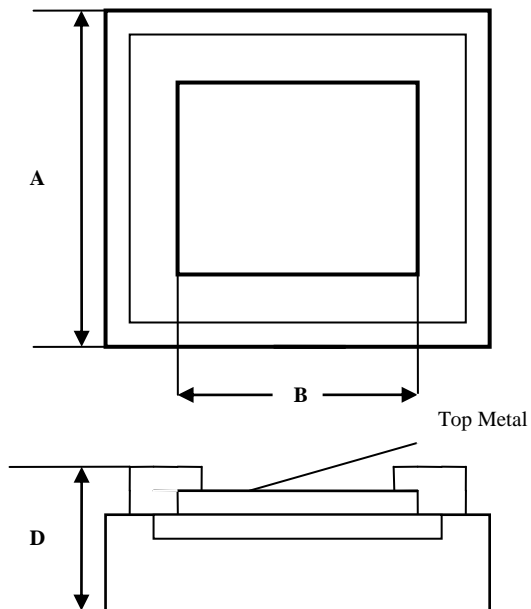
Electrical Characteristics	Symbol	Unit	Spec. limit	Die Sort
Breakdown Voltage @ $I_R=0,10\text{mA}$	$V_B$	V	600	620
Average Rectified Forward Current	$I_{F(AV)}$	A	8,0	-
DC Forward Voltage @ $25^\circ\text{C}, I_F=8,0\text{A}$	$V_F$	V	1,35	1,3
Maximum Reverse Current @ $25^\circ\text{C}, V_R=600\text{V}$ @ $125^\circ\text{C}, V_R=600\text{V}$	$I_R$	MA	0,010 0,500	0,009 0,450
Reverse Recovery Time, $I_F=1\text{A}, V_R=30\text{V}, di_F/dt=100\text{A/uS.}$	$t_{rr}$	nS	70	65
Operating Junction Temperature	$T_J$	$^\circ\text{C}$	175	



- $di_F/dt$  - Rate of change of current through zero crossing
- $I_{RRM}$  - Peak reverse recovery current
- $t_{rr}$  - Reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current
- $Q_{rr}$  - Area under curve defined by  $t_{rr}$  and  $I_{RRM}$   

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$
- $di_{(rec)M}/dt$  - Peak rate of change of current during  $t_b$  portion of  $t_{rr}$

DIM	ITEM	$\mu\text{m}$
$A_x$ $A_y$	Die Size	2050 2050
D	Thickness	350max.
Scribe line Width		60



*Top metal: Al – for Wi*

*Backside metal: Ti-Ni-Ag – for Soldering.*

[www.vsp-mikron.com](http://www.vsp-mikron.com)

физический съём 1650 кристаллов с пластины